

4224091/A 04/2018

NOTES:

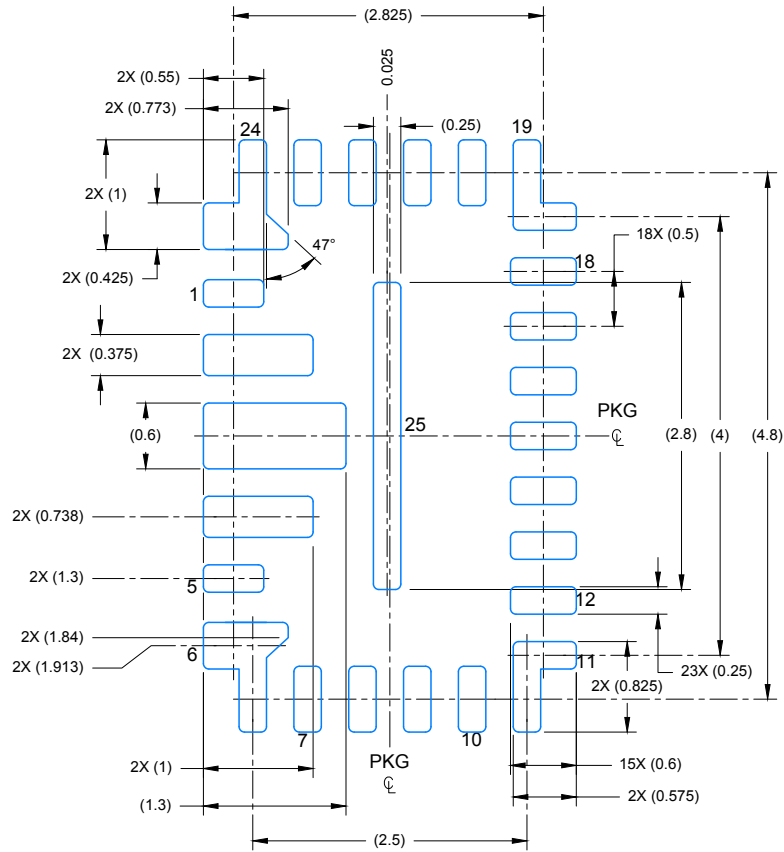
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

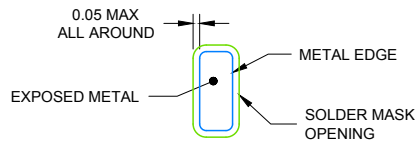
RPB0025A

VQFN-HR - 1 mm max height

PLASTIC QUAD FLAT-NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X



NON SOLDER MASK
DEFINED
SOLDER MASK DETAIL

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NOTES: (continued)

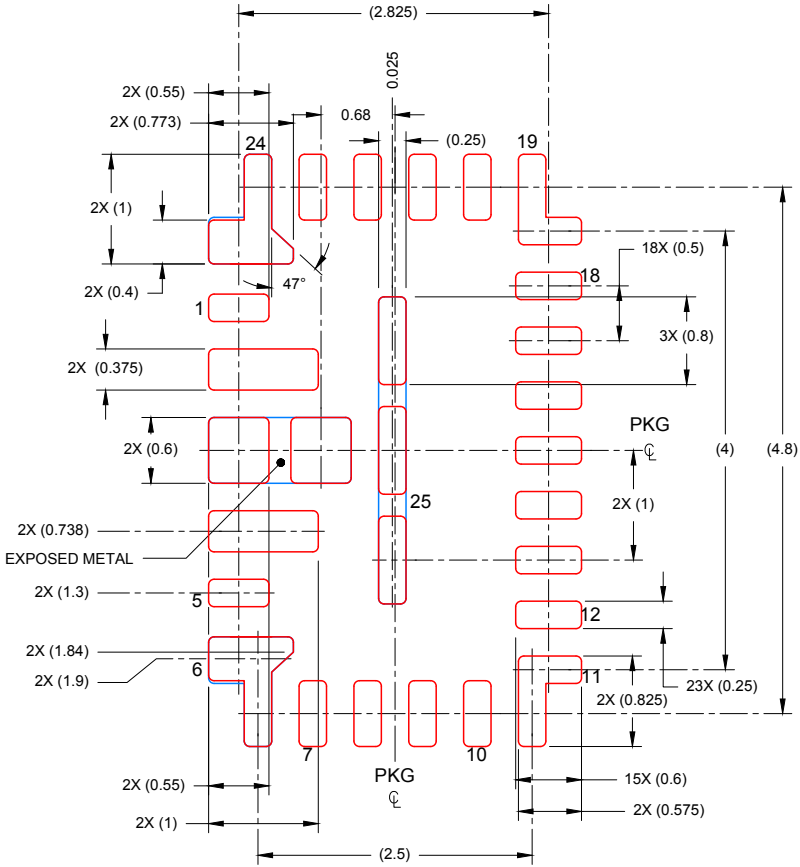
- For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

RPB0025A

VQFN-HR - 1 mm max height

PLASTIC QUAD FLAT-NO LEAD



SOLDER PASTE EXAMPLE
 BASED ON 0.100 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA
 UNDER PACKAGE
 PAD 3, 6, 24 & 25: 87%
 SCALE: 15X

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NOTES: (continued)

- 4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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